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AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning on Page 13, Line 16 with the following rewritten paragraph:

Furthermore, as Figure 5 illustrates, the chips 200, 300, 400 are isolated from each other by foamed chip insulating layers 204, 404 that are interposed between adjacent chips. As described above, these foamed chip insulating layers 204, 404 provide an effective low dielectric constant insulating material that will in turn reduce the capacitive load of electrical interconnects adjacent the insulating layers. In one embodiment, the multichip cube structure 500 further comprises an insulating layer 450 formed on a lower surface 452 of the chip 400. It is generally understood that a high capacitive load is undesirable in certain applications, particularly in densely packaged circuits where it would lead to greater signal delay. Advantageously, the present invention provides a way to decrease the capacitive coupling between adjacent integrated circuit chips in densely packed multichip modules without causing potentially detrimental reduction in mechanical integrity of the structure.

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